



ADPCM Speech Synthesis LSI for Automotive

## GENERAL DESCRIPTION

ML22Q284 is a speech synthesis LSI supporting an in-vehicle quality that incorporates Flash for storing voice code data, and can be controlled with a standalone interface.

By integrating all the functions required for voice output into a single chip, this LSI can be more easily incorporated in compact portable devices.

•	Playback time
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• AEC-Q100:

• Package:

	Product name	Flash capacity (bit)	Maximum playback time	e (sec) (at fs = 6.4 kHz)		
			4-bit ADPCM2	16-bit PCM		
	ML22Q284	692K	27.6	6.9		
N	lotes: Flash capacity	shows the numerical	value of only a voice area	1		
• Spe	ech synthesis metho	d: 4-bit A	DPCM2			
		8-bit N	onlinear PCM			
		8-bit P	CM, 16-bit PCM			
		(Metho	d can be specified for each	h phrase)		
• Flas	h capacity:	692 Kb	692 Kbit			
• San	pling frequency (Fs	b): 8.0/16.	8.0/16.0/32.0 kHz, 6.4/12.8/25.6 kHz, 10.7/21.3 kHz			
		(Can be	e specified for each phrase	:)		
• Spe	aker driving amplifi	er: D-class	amplifier (driven by 8 $\Omega$ )	)		
• CPU	J command interfac	e: Standa	one interface (built-in noi	se removal function)		
• Max	kimum number of pl	rases: 30 phra	ises			
• Dise	connection detection	function /Speaker pi	n short detection function			
• Sou	rce oscillation frequ	ency: 4.096 N	/IHz (Typ) (internal)			
• Pow	ver supply voltage:	2.0 to 5	5.5 V			
• Flas	h memory rewritabl	e time: 80 time	s			
• Ope	rating temperature 1	range: -40 °C	to +105 °C			

Compliant

20-pin plastic TSSOP

(xxx: ROM code No.)

ML22Q284-NNNTD/ML22Q284-xxxTD



The following	table shows	the differences	from	ML22Q274,	ML22Q294
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Parameter	ML22Q284	ML22Q274	ML22Q294
MCU interface	Standalone	Clock synchronization Serial	12C
Flash capacity	692 Kbit	692 Kbit (when 30 phrases are selected) 688 Kbit (when 62 phrases are selected)	←
Playback method	4-bit ADPCM2 8-bit Nonlinear PCM 8-bit PCM 16-bit PCM	←	←
Maximum number of phrases:	30	30/62	$\leftarrow$
Sampling frequency (kHz)	6.4/8.0/10.7/12.8/ 16.0/21.3/25.6/32.0	←	←
Clock frequency	4.096 MHz (internal oscillation)	←	←
Low-pass filter	FIR interpolation filter	$\leftarrow$	$\leftarrow$
Speaker driving amplifier	D-class amplifier	$\leftarrow$	$\leftarrow$
Speaker driving amplifier output load	8Ω	←	<i>←</i>
Speaker driving amplifier output voltage	1 W (Ta = -40 to +85°C) 0.8 W (Ta = -40 to +105°C)	<i>←</i>	$\leftarrow$
Edit ROM function	Yes	$\leftarrow$	$\leftarrow$
Volume control	32 levels	$\leftarrow$	$\leftarrow$
Silence insertion	4 ms to 1024 ms (4 ms/step)	←	←
Repeat function	Yes	$\leftarrow$	$\leftarrow$
Power supply voltage	2.0 to 5.5 V	←	~
Operating temperature range	-40 to +105°C	→	→
Package	20-pin TSSOP	$\leftarrow$	←

FEDL22Q284-04

ML22Q284

## BLOCK DIAGRAMS



## ■ PIN CONFIGURATIONS (TOP VIEW))



## PIN DESCRIPTION

Pin	Symbol	I/O	Initial value (At the RESET_N Input)	Initial value (At standby)	y) Description	
1	SPP	0	Hi-Z	Hi-Z	Positive (+) output pin of the speaker amplifier built-in	
2	SPM	0	Hi-Z	Hi-Z	Negative (-) output pin of the speaker amplifier built-in.	
3	SPGND	-	-	-	Ground pin for the speaker amplifier.	
4	SPVDD	-	-	-	Power supply pin for the speaker amplifier Connect a bypass capacitor of 0.1 $\mu$ F or more between this pin and SPGND pin.	
5	BUSYB	0	Hi-Z	1	BUSY output pin. When BUSYB use mode is set, the "L" level is outputted during playback. When disconnection is detected with disconnection detection function, the "L" level is outputted. BUSYB unused mode and logic inversion can be set with Speech LSI Utility.	
6	DGND	-	-	-	Digital ground pin.	
7	VDDI	-	-	_	Regulator output pin for internal logic circuitry.	
8	DVDD	-	-	-	Connect a capacitor of 10 $\mu$ F or more between this pin and DGND pin Digital power supply pin. Connect a capacitor of 0.1 $\mu$ F or more between this pin and DGND pin.	
13	EVIN0	I			Command input pin.	
14	EVIN1	I			Voice can be played back and stopped based on a change in a signal	
15	EVIN2	Ι	0	0	The pin state can be set with Code Option Setting when a voice code	
16	EVIN3	I	0	0	is generated.	
17	EVIN4	Ι			EVINO pin: select pull-up input or high impedance input EVIN4-1 pin: select pull-down input, pull-up input, or high impedance input	
18	VPP	-	-	-	Power supply pin for rewriting Flash memory. Fix this pin to GND except when rewriting Flash memory	
19	TEST	I	0	0	Test pin. Fix this pin to DGND.	
20	RESET_N	I	0	1	Reset pin. Input "L" level for initialization, when power is turned on, or when voltage falls below recommended operation power supply voltage range. After the power supply voltage is stable, drive this pin to "H" level.	
9 10 11 12	N.C.	-	-	-	Unused pin. Leave this pin open.	

## ABSOLUTE MAXIMUM RATINGS

				(DGND = 0 V)
Parameter	Symbol	Condition	Rating	Unit
Power supply voltage	DV <sub>DD</sub> SPV <sub>DD</sub>		-0.3 to + 7.0	V
Internal logic power supply voltage	Vddl	Ta = 25 °C	-0.3 to +3.6	V
Flash power supply voltage	VPP		-0.3 to +9.5	V
Input voltage	VIN		-0.3 to V <sub>DD</sub> +0.3	V
Power dissipation	PD		1	W
Output short-circuit current	Isc1	Applied to pin other than SPP or SPM	-12 to +11	mA
- 1	Isc2	SPP pin, SPM pin	600	mA
Storage temperature	Tstg	-	-55 to +150	°C

## RECOMMENDED OPERATING CONDITIONS

				(DGND = 0 V)	
Parameter	Symbol	Condition	Range	Unit	
	DV <sub>DD</sub>	-	2.0 to 5.5		
Power supply voltage	SPVDD	Flash memory write	2.7 to 5.5	V	
Flash power supply voltage	VPP	Flash memory write	7.7 to 8.3	V	
Flash memory rewrite cycles	N	-	80	times	
Operating temperature range	T <sub>OP1</sub>	-	-40 to +105		
	T <sub>OP2</sub>	Flash memory write	0 to +40	30	

## ELECTRICAL CHARACTERISTICS

### • DC Characteristics

		$DV_{DD}$ = $SPV_{DD}$ = 2.0 to 5.5 V, [	DGND = SPGI	ND = 0 V, 1	Га = -40 to +	105°C
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
"H" input voltage	VIH	-	0.7 × DV <sub>DD</sub>	-	DVDD	V
"L" input voltage	VIL	-	0	-	0.3 × DV <sub>DD</sub>	V
"H" output voltage 1	V <sub>OH1</sub>	$I_{OH} = -0.5 \text{ mA}$	DV <sub>DD</sub> -0.5	-	-	V
"L" output voltage 1	V <sub>OL1</sub>	I <sub>OL</sub> = 0.5mA	-	-	0.5	V
"H" input current 1	I <sub>IH1</sub>	V <sub>IH</sub> = DV <sub>DD</sub>	-	-	1	μA
"H" input current 2	Іін2	V <sub>IH</sub> = DV <sub>DD</sub> TEST pin	0.02	0.3	1.5	mA
"H" input current 3	Іінз	V <sub>IH</sub> = DV <sub>DD</sub> EVIN4-1 terminal pull-up input is set	0.02	0.3	1.5	mA
"L" input current 1	IIL1	VIL = DGND	-1	-	-	μA
"L" input current 2	I <sub>IL2</sub>	Vı∟ = DGND RESET_N pin	-1.5	-0.3	-0.02	mA
"L" input current 3	I <sub>IL3</sub>	V <sub>IL</sub> = DGND EVIN4-0 terminal pull-up input is set	-1.5	-0.3	-0.02	mA
"H" output current 1	I <sub>OOH1</sub>	VOH= DV <sub>DD</sub> = SPV <sub>DD</sub> (High impedance) BUSYB, SPP, SPM pin	-	-	1	μA
"H" output current 2	Іоон2	VOH= DV <sub>DD</sub> (Nch Open drain) BUSYB pin	-	-	1	μΑ
"L" output current 1	I <sub>OOL1</sub>	VOL=DGND=SPGND (High impedance) BUSYB, SPP, SPM pin	-1	-	-	μΑ
"L" output current 2	I <sub>OOL2</sub>	VOL=DGND (Pch Open drain) BUSYB pin	-1	-	-	μΑ
Supply current during	I <sub>DD1</sub>	No output load DVpd= SPVpd=3.0 V	-	4.0	6.0	m۸
playback	IDD2	No output load DVpp= SPVpp=5.0 V	-	6.0	10	IIIA
Supply current during stabilizing chattering	I <sub>DDC1</sub>	DV <sub>DD</sub> =SPV <sub>DD</sub> =5.0 V	-	3.0	5.0	mA
	IDDS1	Ta ≤ 40°C	-	0.5	3.0	
Standby supply current	IDDS2	Ta ≤ 85°C	-	0.5	8.0	μA
	IDDS3	Ta ≤ 105°C	-	0.5	16.0	
Source oscillation frequency	fana	-10 to +50°C	4.034	4.096	4.158	
	IUSC	-40 to +105°C	3.973	4.096	4.219	

## • Characteristics of Analog Circuitry

		$DV_{DD} = SPV_{DD} = 2.0$ to 5.5	5 V, DGND = 5	SPGND = 0 V,	Ta = -40 to +	105°C
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
SPM, SPP output load resistance	Rlsp	-	8	-	-	Ω
Speaker amplifier output	Pspo	SPV <sub>DD</sub> = 5.0 V, Sin wave f = 1 kHz R <sub>LSP</sub> = 8 Ω, THD ≥ 10% Ta = -40 to +85°C	-	1.0	-	W
voltage		SPV <sub>DD</sub> = 5.0 V, Sin wave f = 1 kHz R <sub>LSP</sub> = 8Ω, THD ≥ 10% Ta = -40 to +105°C	-	0.8	-	W

#### • AC Characteristics

DVDD	$o = SPV_{DD} = 2$	2.0 to 5.5 V, DGND = S	PGND =	0 V, Ta =	= -40 to +	105°C
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
RESET_N input pulse width	t <sub>RST</sub>	-	100	-	-	μs
Start time SPV <sub>DD</sub> after starting DV <sub>DD</sub>	t∨DD	-	0	-	-	ns
Initialization time after reset release	t <sub>INIT</sub>	-	-	-	65	ms
Oscillation stable time	t <sub>PUP1</sub>	-	-	1	2	ms
Playback time	tvcyc	-	20	-	-	ms
Chattering removal time <sup>*1</sup>	t <sub>SP</sub>	Initial value (08 h)	Тур2	16	Typ.+2	ms
Command processing time	t <sub>B1</sub>	-	-	-	400	μs
Oscillation stop time, after playback	t <sub>osst</sub>	-	-	-	500	μs
Next command transmit time□ In the case of the playback	t <sub>NCM</sub>	-	-	-	10	ms
Next command transmit time after shifting to a standby state	tсмs	-	50	-	-	ns
Disconnection judging by the DISCONNECT command start time	t <sub>DCDS</sub>	-	1.5	-	-	ms
Disconnection judging by the DISCONNECT command end time	<b>t</b> dcde	-	-	-	1	s
BUSYB change time from "L" to "H", after over-current detection of a speaker amplifier	tsp	-	-	-	80	μs
Processing time before playback start	t <sub>PLBF</sub>	-	0.3	-	2.1	ms
Processing time after playback start	<b>t</b> PLAF	-	0.15	-	1.2	ms
Fade-out time at Change Immediately mode or Change Immediately Once mode	t <sub>FDO</sub>	-	-	22	-	ms

Note 1 : Can be set within a range from 0 ms to 62 ms with Speech LSI Utility. Note : Output pin load capacitance = 45 pF (max.)

## FUNCTIONAL DESCRIPTION

#### • Standalone interface

Standby is canceled by a change in a signal input to the EVIN4-0 pin, and after the chattering removing period, an operation corresponding to a command indicated by the EVIN4-0 pin starts.

The pin status of the EVIN0 pin can be selected between high-impedance input (Hi-Z) and pull-up input (PullUp). The pin status of the EVIN4-1 can be selected among high-impedance input (Hi-Z), pull-down input (PullDown), and pull-up input (PullUp).

The pin status of the EVIN4-0 pin is selected using Speech LSI Utility. Please refer to a "Code Option Setting Item" for details.

#### • Chattering removal time

Chattering removal time can be set for preventing erroneous operation due to chattering when the EVIN4-0 pin changes. The time can be set from 2 ms to 62 ms (setting value: 01h to 1Fh) in increments of 2 ms. The initial value is 16 ms (08h).

Chattering removal time =  $(2^4*bit4+2^3*bit3+2^2*bit2+2^1*bit1+2^0*bit0)*2$  ms

Set a setting value 10h to set the time to be 32 ms.

Chattering removal time =  $2^{4*1+2^{3*0+2^{2*0+2^{1*0+2^{0*0}}}}$  + 4 ms =  $8^{2*2}$  ms = 32 ms

The chattering removal time is selected using Speech LSI Utility. Please refer to a "Code Option Setting Item" for details.

#### • Speech synthesis method

Supporting four types of speech synthesis methods, which are 4bit ADPCM2, 8-bit nonlinear PCM, 8-bit PCM, and 16-bit PCM. Any of these can be selected based on the characteristics of the voice to be played back.

Speech synthesis method	Compression rate <sup>*1</sup>	Suitable waveform	Characteristics
4-bit ADPCM2	1/4	Normal voice sound wave	Unique scheme which is a refined version of 4bit ADPCM Offers higher sound quality with better waveform followability.
8-bit Nonlinear PCM	1/2	Sound including high frequency components	A part around the center of the waveform is played back with a sound quality equivalent to 10 bits.
8-bit PCM	1/2	(such as sound effects)	Normal 8-bit PCM.
16-bit PCM	1		Normal 16-bit PCM.

Note 1: When the same sampling frequency is used.

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Memory Allocation and Creating Voice Data

The voice code data consists of a voice management area, a voice data area, and an edit ROM area.

The voice control area manages voice data for 30 phrases.

The voice area contains actual waveform data.

The edit ROM area contains data for effective use of voice data. For the details, refer to the section of "Edit ROM Function". The edit ROM area only available when the edit ROM is used.

The ROM data is created using Speech LSI Utility.

Please refer to a "Code Option Setting Item" for details.

0x00000	Voice control area
0x001FF	
0x00200	
	Voice data area / Edit ROM area <sup>*1</sup>
0x159FF	

## Voice code data configuration

\*1: Edit ROM area depends on creation of the data

## • Playback Time and Flash Capacity

The playback time depends on the memory capacity, sampling frequency, and the playback method. The equation to know the playback time is shown below. But this is not applied if the edit ROM function is used.

Playback time [sec] = 1.024 × (Voice data area/Edit ROM area) (Kbit) Sampling frequency [kHz] × Bit length

(Bit length is 4 at the 4-bit ADPCM2 and 8/16 at the PCM.)

In the case that the sampling frequency is 8 kHz, algorithm is 4-bit ADPCM2, the playback time is approx. 22.1 seconds.

Playback time =  $\frac{1.024 \times 692(\text{Kbit})}{8(\text{kHz}) \times 4(\text{bit})} \approx 22.1 \text{ [sec]})$ 

Make the playback time of one phrase more than 20 msec.

#### • Edit ROM function

The edit ROM function makes it possible to play back multiple phrases in succession. The following functions are set using the edit ROM function:

- Continuous playback: There is no limit to set the number of times of the continuous playback. It depends on the Flash capacity only.
- Silence insertion function: 4 ms to 1,024 ms
  - \*Note: Silent insertion time varies for  $\pm 1$  ms depends on the sampling frequency. An independent phrase generated by edit ROM shall be 20 ms or longer.

It is possible to use voice ROM effectively to use the edit ROM function. An example of the ROM structure, in a case of using the edit ROM function is as follows.

	i / 5 -
Phrase 2	A A D
Phrase 3	A C D
Phrase 4	E B D
Phrase 5	E C D
Phrase 6	A A B D Silence (4 ms) E C D
Phrase 7	Silence (20 ms)

Example 1) Phrases using the Edit ROM Function

#### Example 2) Structure of the ROM storing contents of Example 1



\*1: Information on phrases 2 to 7 stored

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#### ML22O284

#### Playback mode setup

Five playback modes are available. Can be set up for every phrase. Set when the voice code data is generated.

### Play Once mode

This mode is playback once.



Next command must be input in the standby state after the playback ends.



### Scheduled Play Once mode

This mode is playback once.

When the next phrase is inputted during playback, after playback of the present phrase ends, playback of the next phrase starts. When the following phrase is inputted into playback, after playback of the present phrase is completed, playback of th following phrase starts.



When a plurality of commands are input, the last command input at the end of the phrase is valid. In the following case, the phrase (n) is not played back because the last command is STOP command.



#### Change Immediately Once mode

This mode is for playing back once.

When the following phrase is inputted into playback, playback of the present phrase is ended on the way, and playback of the following phrase starts.



When a plurality of commands are input, the last command input at the end of the phrase is valid. In the following case, the last input phrase (o) is played back.



#### Scheduled Play mode

Once the playback starts, it is repeated until the next command is input.

The next command input during the playback is executed after the playback ends.

When a plurality of commands are input, the last command input at the end of the phrase is valid, as in Scheduled Play Once.



#### Change Immediately mode

Once the playback starts, it is repeated until the next command is input.

When the next command is input, the phrase being played back is terminated, and the next command is executed. When the following command is inputted into playback, playback of the present phrase is ended on the way, and playback of the following command starts.

When a plurality of commands are input, the last command input at the end of the phrase is valid, as in Change Immediately Once.



\*1: When used with default "H" level, CMOS output

#### • Volume setup function

Value	Volume [dB]	Value	Volume [dB]	Value	Volume [dB]
00h	+2.98	0Ah	-0.41	15h	-6.87
01h	+2.70	0Bh	-0.83	16h	-7.79
02h	+2.40	0Ch	-1.28	17h	-8.82
03h	+2.10	0Dh	-1.75	18h	-9.99
04h	+1.78	0Eh	-2.25	19h	-11.34
05h	+1.45	0Fh	-2.77	1Ah	-12.94
06h	+1.11	10h	-3.34	1Bh	-14.90
07h	+0.76	11h	-3.94	1Ch	-17.44
08h	+0.39	12h	-4.58	1Dh	-21.04
09h	+0.00	13h	-5.28	1Eh	-27.31
		14h	-6.04	1Fh	OFF

Each phrase can set up the volume setup. Set when the voice code data is generated.

• Function of setting wait time before and after playback (WS1, WS2, WS3, WS4)

Wait time before playback (WS1, WS2) and after playback (WS3, WS4) can be set for each phrase. Set when the voice code data is generated.



WS1: Time after inputting a phrase address, until SPP/SPM pins are enabled.

WS2: Time after SPP/SPM pins are enabled, until playback is started.

WS3: Time after playback is completed, until SPP/SPM pins are disabled.

WS4: Time after SPP/SPM pins are disabled, until it will be in a standby state.

WS1-WS4 can be arbitrarily set up between 0 to1020 ms (4 ms unit).

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#### Speaker Pin Short Detection Function ٠

The speaker pin short detection function detect the short-circuit between SPP pin and SPM pin, or between SPP/SPM pin and GND during playback.

When short-circuit of a speaker pin is detected, the playback will be stopped automatically, BUSYB pin will become "H" level, and LSI will become in a standby state.

Speaker short detection prevents IC destruction, but the detection circuit is effective to prevent destruction caused by sudden accidents, and is not intended for use in the condition like short detection occurs continuously. This function can be set up with the option screen of Speech Utility.

Please refer to a "Code Option Setting Item" for details.



\*1: When used with default "H" level, CMOS output

## Commands

The following commands are used for the LSI. After setting the voice code data in the flash memory of this LSI, be sure to use the voice playback command.

Command	Description
	Stop command.
STOP	The STOP command becomes effective for phrase other than those in Play Once mode and Scheduled Play Once mode.
	Disconnection detection command.
DISCONNECT	Speaker disconnection is detected. The STOP command must be input after using the DISCONNECT command.
	Playback command.
PIRASE	Playback phrase is selected from 30 phrases.

### • Command configuration

Command is of 1 byte, and any bit sequence can be set for STOP command and DISCONNECT command. PHRASE command is allocated with a bit sequence other than the set values for STOP command and DISCONNECT command.

These are set when the voice code data is generated. Please refer to a "Code Option Setting Item" for details.

The command configuration when the initial value (STOP command is set to be 00000b and DISCONNECT command is set to be 00001b) is set is as follows.

Command	EVIN4	EVIN3	EVIN2	EVIN1	EVIN0
STOP	0	0	0	0	0
DISCONNECT	0	0	0	0	1
	0	0	0	1	0
PHRASE			:		
	1	1	1	1	1

Example where STOP command is set to 11111b and DISCONNECT command is set to 00001b is described. When STOP command is changed from the initial value, the number of phrase available decreases by one.

Command	EVIN4	EVIN3	EVIN2	EVIN1	EVIN0
-* <sup>1</sup>	0	0	0	0	0
DISCONNECT	0	0	0	0	1
	0	0	0	1	0
PHRASE			:		
	1	1	1	1	0
STOP	1	1	1	1	1

Note 1: 00000b cannot be set to PHRASE command. 29 phrases from 00010b to 11110b can be set to PHRASE command.

#### STOP command

EVIN4-0 pin	EVIN4	EVIN3	EVIN2	EVIN1	EVIN0
Initial value	0	0	0	0	0

The STOP command is used to stop the playback. BUSYB pin will become "H", if the playback is stopped. The STOP command becomes effective for the phrase waiting to be played in Scheduled Play Once mode, and in Scheduled Play modem, Change Immediately Once mode, and Change Immediately mode.

STOP command used for phrases played back in Play Once mode or Scheduled Play Once mode, the STOP is ignored. When STOP command is input in Scheduled Play mode, the playback stops after the phrase is played back to the end. When STOP command is input in Change Immediately Once mode or Change Immediately mode, the voice fades out, and the playback stops.

Input a phrase playback request (PHRASEn command) after the STOP command, after confirming the end of the phrase being played (BUSYB="H"), and after  $t_{OSST}+t_{CMS}$  has elapsed.

Operations where STOP command is effective are described below.

### STOP command operation in the case of Scheduled Play Once mode



\*1: When used with default "H" level, CMOS output

#### • STOP command operation in the case of Scheduled Play mode



STOP command operation in the case of Change Immediately Once mode or Change Immediately mode



#### DISCONNECT command

EVIN4-0 pin	EVIN4	EVIN3	EVIN2	EVIN1	EVIN0
Initial value	0	0	0	0	1

The DISCONNECT command is used to diagnose whether the speaker is disconnected or not.

The command cannot be used during voice playback. The command shall be used during standby (no playback). Disconnection detection result is output to BYSYB pin. "L" is output when the speaker is disconnected, and outputs "H" when the speaker is not disconnected. Please input the STOP command to transition to standby state, after you use the DISCONNECT command.



When no STOP command is input after the execution of DISCONNECT command, the disconnection detection automatically stops in one second, and transition to standby occurs.



#### • PHRASE command

EVIN4-0 pin	EVIN4	EVIN3	EVIN2	EVIN1	EVIN0
	0	0	0	1	0
Initial value			:		
	1	1	1	1	1

PHRASE command is playback command. Specifies an address of a phrase to be played back. Command that is not set to be STOP command or DISCONNECT command is set to be PHRASE command. An address of phrase to be played back is set when voice code data is generated with Speech LSI Utility.

Timings of PHRASE command are shown below.

EVIN4-0		Phrase		
			-	
BUSYB*1			i	
SPP/SPM			1	
	Hi-Z		ł	
Status	Standby	Stabilizing chattering	İ.	Playing
				Command processing

Command processing

\*1: When used with default "H" level, CMOS output

## TIMING DIAGRAMS

• Power-On Timing



Turn on DVDD and SPVDD simultaneously, or turn on SPVDD after turning on DVDD. Turn on DVDD and SPVDD simultaneously, or turn on SPVDD after turning on DVDD. When DV<sub>DD</sub> or SPV<sub>DD</sub> falls below recommended operation power supply voltage range, "L" level must be input to RESET\_N pin.



• Power down timing (RESET\_N pin)

When  $DV_{DD}$  or  $SPV_{DD}$  falls below recommended operation power supply voltage range, "L" level must be input to RESET\_N pin.

#### • Play Oncemode/Scheduled Play Once/Change Immediately Once timing

After playback of phrase (m) ends, playback request for next phrase (n) is accepted and the phrase (n) is played back. All the commands become invalid during playback of phrase (m). After BUSYB has shifted to "H" level, input the PHRASE command after  $t_{OSST}+t_{CMS}$  has elapsed.

EVIN4-0	× •	Phras	se (m)			
_		Phrase de	etermined			
BUSYB <sup>*1</sup> VOH		t <sub>B1</sub>	<u>}</u>			
(internal)		scillating				
Speaker enable (internal)	Stabilizing oscillation		WS1 WS2	t <sub>PLBF</sub>	t <sub>VCYC</sub>	
SPP —	Hi-Z				-	
SPM —	Hi-Z					
Status \	Stabilizing chattering	ommand ocessing	Play	/ing		
-	Standby					
$\checkmark$						
EVIN4-0	Phrase (m)		•	Phras	e (n)	
			, , ,	Phrase	edetermined	
BUSYB <sup>*1</sup> VOH VOL		t <sub>CMS</sub> t <sub>PUI</sub>	P1 t <sub>SP</sub>	t <sub>B1</sub>		
OSC (internal)	Oscillating	$\lambda$	X		Oscillating	
	t <sub>PLAF</sub> WS3 WS4 t <sub>OSS</sub>	_/\/ \ T		V	VS1 WS2 t <sub>PLBF</sub>	
Speaker enable (internal)			Stabilizing			
(,			I			
SPP			Hi-Z			
SPM			Hi-Z			
Status	Playing	X_X	×	()X	· · ·	Playing
Aw	aiting oscillation stop	Stat	bilizing chatt	ering Co	ommand process	sing
	Standby	_		*1:Used with	n default "H" Level,	CMOS output

• Scheduled Play Once mode and Scheduled Play mode Timing (Continuous Play)

In response to playback request for the next phrase (n), the phrase (m) is played back to the end, and then playback of the phrase (n) starts.



\*Under Scheduled Play mode, playback is stopped by STOP command.

Note 1: In Scheduled Play Once mode, the phrase (n) is played back immediately after the end of the playback of the phrase (m), in response to an input of a playback request (PHRASE command) for the next phrase (phrase (n)) within t<sub>NCM</sub>.

• Change Immediately Once mode and Change Immediately mode Timing (Continuous Play)

In response to playback request for the next phrase (n), the phrase (m) is played back to the last, and then playback of the phrase (n) starts.



·Under Change Immediately mode, playback is stopped by STOP command.



After STOP command is input, the phrase is played back until the end, and the playback stops.



\*1: Used with default "H" Level, CMOS output

Change Immediately Once mode and Change Immediately mode voice stop timing

After STOP command is input, the voice fades out, and the playback stops.







• Speaker short detection timing



\*1: Used with default "H" Level, CMOS output

## Code Option Setting Item

Items set on Code Option Setting screen for Speech LSI Utility are as follows.

## •Speaker pin short detection function setting

Lies of analysis nin abort detection function	□ (Not used)
Use of speaker pin short detection function	□ (Used)

### ·Command setting

Command type	○1 byte (communicate with 1-byte command)
Command type	⊖ <del>2byte</del> (cannot be set)

STOP/DISCONNECT Command	Command bit sequence		
○ Standard	STOP command	Use 0_0000b	
U Stanuaru	DISCONNECT command	Use 0_0001b	
	STOP command	Set any bit sequence	
⊖Custom	DISCONNECT command	Set any bit sequence	
		(Set value different from STOP command)	

## BUSYB Pins Setting

Use of BUSYB	Initial State	Condition	BUSYB pin status
□ (Not used)	OL level Output	*	Fixed to "L" output
	○H level Output	*	Fixed to "H" output
□ (Used)	⊖L level Output	OCMOS	Output initial value "L" with CMOS output
		⊖Nch Open Drain	Output initial value "L" with Nch open drain output
		⊖Pch Open Drain	Output initial value HiZ with Pch open drain output
		⊖Hi-Z	Hiz output
	⊖H level Output	OCMOS	Output initial value "H" with CMOS output
		ONch Open Drain	Output initial value HiZ with Nch open drain output
		⊖Pch Open Drain	Output initial value "H" with Pch open drain output
		⊖Hi-Z	Hiz output

\*: Setting value invalid

## •EVIN4 to EVIN0 Pins Setting

EVIN4-1	⊖Hi-Z	Used with high impedance input
	○ Pull Down	Used with pull-down input
	⊖Pull-up	Used with pull-up input
	⊖Hi-Z	Used with high impedance input
EVINO	⊖ <del>Pull Down</del>	Used with pull-down input (cannot be set)
	⊖Pull-up	Used with pull-up input

## ·Chattering removal time setting

Chattering removal time	Set chattering removal time within a range of 2 ms to 62 ms (initial value is 16 ms))
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## Event Setting Item

Items set on Event Setting screen for Speech LSI Utility are as follows.

Playback mode

Set playback mode suitable for target playback, with reference to "Playback mode" in FUNCTIONAL DESCRIPTION.

•Volume setup

Set playback mode suitable for target playback, with reference to "Volume setup function" in FUNCTIONAL DESCRIPTION.

• Setting Wait time before and after volume playback

Set desired Wait time with reference to "Function of setting wait time before and after playback (WS1, WS2, WS3, WS4)".

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## TERMINATION OF THE VDDL PIN

The VDDL pin is the regulator output that is power supply pin for the internal logic circuits. Connect a capacitor between this pin and the ground in order to prevent noise generation and power fluctuation.

The recommended capacitance value is shown below. However, it is important to evaluate and decide using the own board.

Also, start the next operation after each output voltage is stabilized.

Pin	Recommended capacitance value	Remarks
VDDL	10 μF ±20%	The larger the connection capacitance, the longer the settling time.

## POWER SUPPLY WIRING

The power supplies of this LSI are divided into the following two:

- Power supply for logic circuitry (: DVDD)
- Power supply for speaker amplifier (: SPVDD)

The example of power connection is shown below



- Turn on DVDD and SPVDD simultaneously, or turn on SPVDD after turning on DVDD.

- Turn off DVDD and SPVDD simultaneously, or turn off DVDD after turning on SPVDD.

FEDL22Q284-04

## ML22Q284

## APPLICATION CIRCUIT



## PACKAGE DIMENSIONS



#### Notes for Mounting the Surface Mount Type Package

The surface mount type packages are very susceptible to heat in reflow mounting and humidity absorbed in storage. Therefore, before you perform reflow mounting, contact a ROHM sales office for the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).

PCB Layer	JEDEC 4layers	JEDEC 2layers
РСВ	(W/L/t= 76.2 / 114.3 / 1.6 (mm))	
Air cooling conditions	Calm(0m/sec)	
Heat resistance ( $\theta$ ja)	63.7[°C /W]	69.4[°C/W]
Heat resistance ( $\theta$ jc)	0.46[°C/W]	0.48[°C/W]
Maximum power consumption of LSI (PMax) At 1W into 8Ω playback	0.28[W]	

TjMax of this LSI is 125 °C. TjMax is expressed with the following formulas. TjMax=TaMax+ $\theta$  ja × PMax

FEDL22Q284-04





[単位/Unit:mm]

実装基板のフットパターンの設計の際には、実装の容易さ、接続の信頼性、配線の引き回し、 半田ブリッジ発生のないことなどを十分考慮してください。

フットパターンの最適な設計は基板材質、使用する半田ペースト種類、厚み、半田付け方法 などによって変わってきます。従って、本パッケージの端子の存在し得る範囲を「半田付け部 端子存在範囲図」として示しますので、フットパターン設計の参考資料としてください。

When laying out PC boards, it is important to design the foot pattern so as to give consideration to ease of mounting, bonding, positioning of parts, reliability, wiring, and elimination of solder bridges.

The optimum design for the foot pattern varies with the materials of the substrate, the sort and thickness of used soldering paste, and the way of soldering. Therefore when laying out the foot pattern on the PC boards, refer to this figure which mean the mounting area that the package leads are allowable for soldering to PC boards.

## REVISION HISTORY

	Date	Page			
Document No		Previous	Current	Description	
		Edition	Edition		
FEDL22Q284-01	Mar 5, 2021	—		Formal 1st edition.	
FEDL22Q284-02	Mar 30, 2021	6	6	SPP, SPM terminal output short-circuit current value change.	
				(Before change) 300mA	
				(After change) 600mA	
FEDL22Q284-03	Oct 4, 2021	15	15	Speaker short-circuit detection warning added.	
		16	16	Added a note on using commands.	
		17	17	Added a note on phrase playback after the STOP command.	
		21	21	Added a note for phrase playback after transitioning to BUSYB "H"	
				level.	
		31	31	Describe the thermal resistance information of the package.	
		-	32	Added "Mounting area for package lead soldering to PC boards".	
FEDL22Q284-04	Jun 29, 2022	31	31	Removed "(SSOP16)" notation for PACKAGE DIMENSIONS.	

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## LAPIS Technology Co., Ltd.

2-4-8 Shinyokohama, Kouhoku-ku, Yokohama 222-8575, Japan https://www.lapis-tech.com/en/